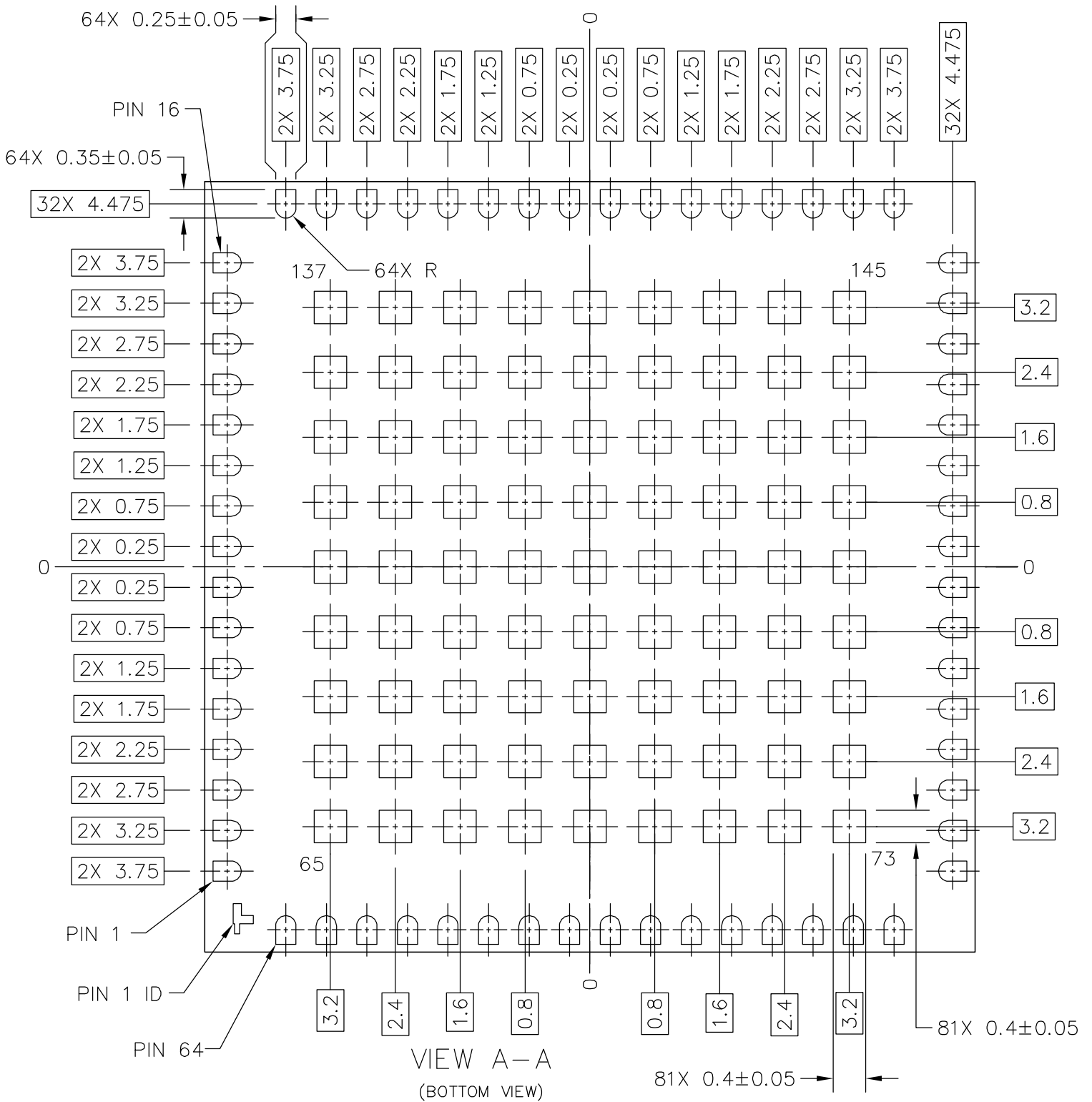


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	SOT1765-1	14 MAR 2016



NOTES:

1. CONTROLLING DIMENSION: MILLIMETERS
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. 

$\varnothing$	0.1 (M) A B C
	0.05 (M) A

 APPLIES TO ALL PAD LOCATIONS.

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